FORM PTO-1449 (REV. 7-80) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO.	SERIAL NO.
LIST OF DOCUMENTS CITED BY APPLICANT *(Use several sheets if necessary)*	TI-34032A	~~TBD~~ 10/761679
	APPLICANT: Chiu et al.	
	FILING DATE ~~Herewith~~ 01/20/04	GROUP 2831 ~~TBD~~

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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.